



Product Change Notification

Change Notification #: 118426-00
Change Title: Select Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack,
PCN 118426-00, Label,
Label Update
Date of Publication: August 13, 2021

Key Characteristics of the Change:

Label, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 12, 2021
--	--------------------

Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

- Customer label updated with UKCA logo added to the label.

Before



After



Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU512GZX1	99A39N
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU010TZX1	99A39P
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU020TZX1	99A39R
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU512GZ	99A42F
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU010TZ	99A42G
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU020TZ	99A42H
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU512GZN1	99A428
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU010TZN1	99A42C
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU020TZN1	99A42D

PCN Revision History:

Date of Revision:

August 13, 2021

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

118426-00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asco.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2021. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos.

Learn how to use Intel Trademarks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.